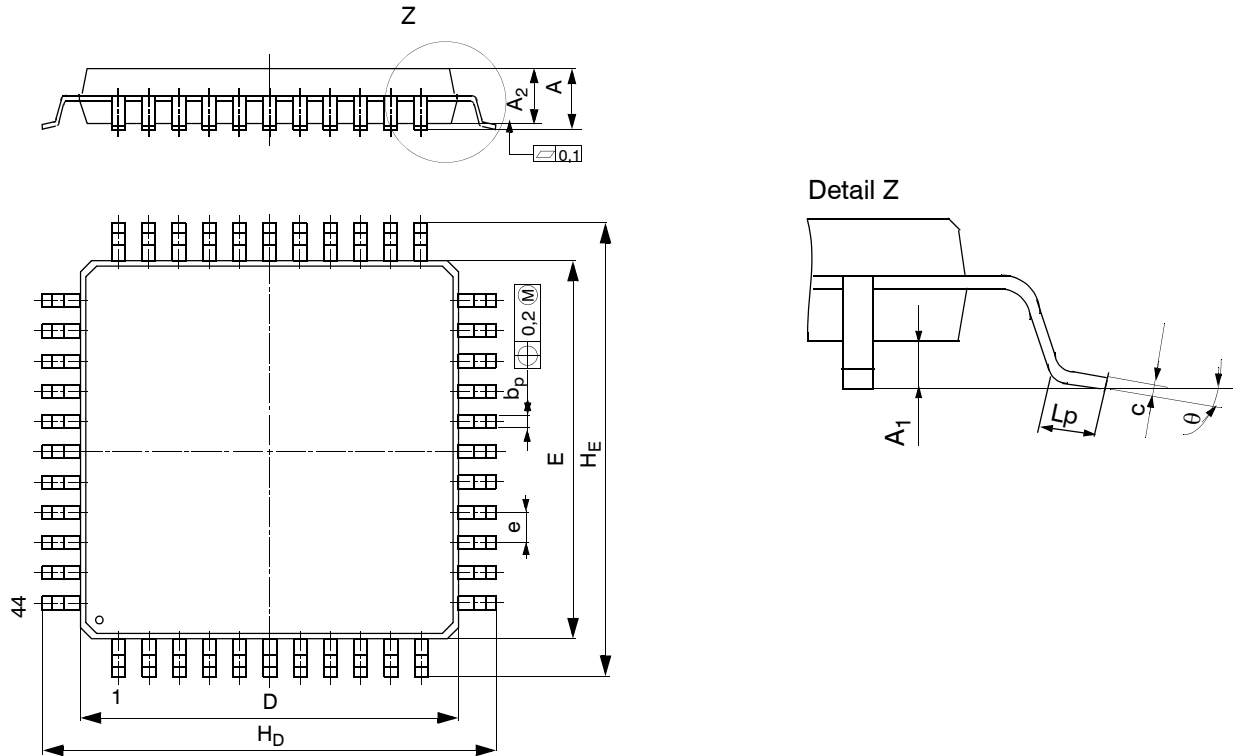
	<b>Package LQFP44 (10 x 10)</b>	<b>MDS 758</b>
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Dimensions in millimetres

Supersedes  
Edition 12.99

Based on JEDEC JEP95: MS-026

**1 Dimensions**


Dimensions of Sub-Group B1	
$e_{nom}$	0,80
$A_{max}$	1,60
$b_{pmin}$	0,30
$b_{pmax}$	0,45
$H_{Emin}$	11,85
$H_{Emax}$	12,15
$H_{Dmin}$	11,85
$H_{Dmax}$	12,15
$L_{pmin}$	0,45

**2 Weight**  $\leq 0,5$  g**3 Package Body Material** Low Stress Epoxy**4 Lead Material** FeNi-Alloy or Cu-Alloy**5 Lead Finish** solder plating**6 Lead Form** Z-bends

Dimensions of Sub-Group C1	
$A_{min}$	-
$A_{1min}$	0,05
$A_{1max}$	0,15
$A_{2min}$	1,35
$A_{2max}$	1,45
$c_{min}$	0,09
$c_{max}$	0,20
$D_{min}^*$	9,75
$D_{max}^*$	10,25
$E_{min}^*$	9,75
$E_{max}^*$	10,25
$\theta_{min}$	0°
$\theta_{max}$	7°

\* without mold-flas

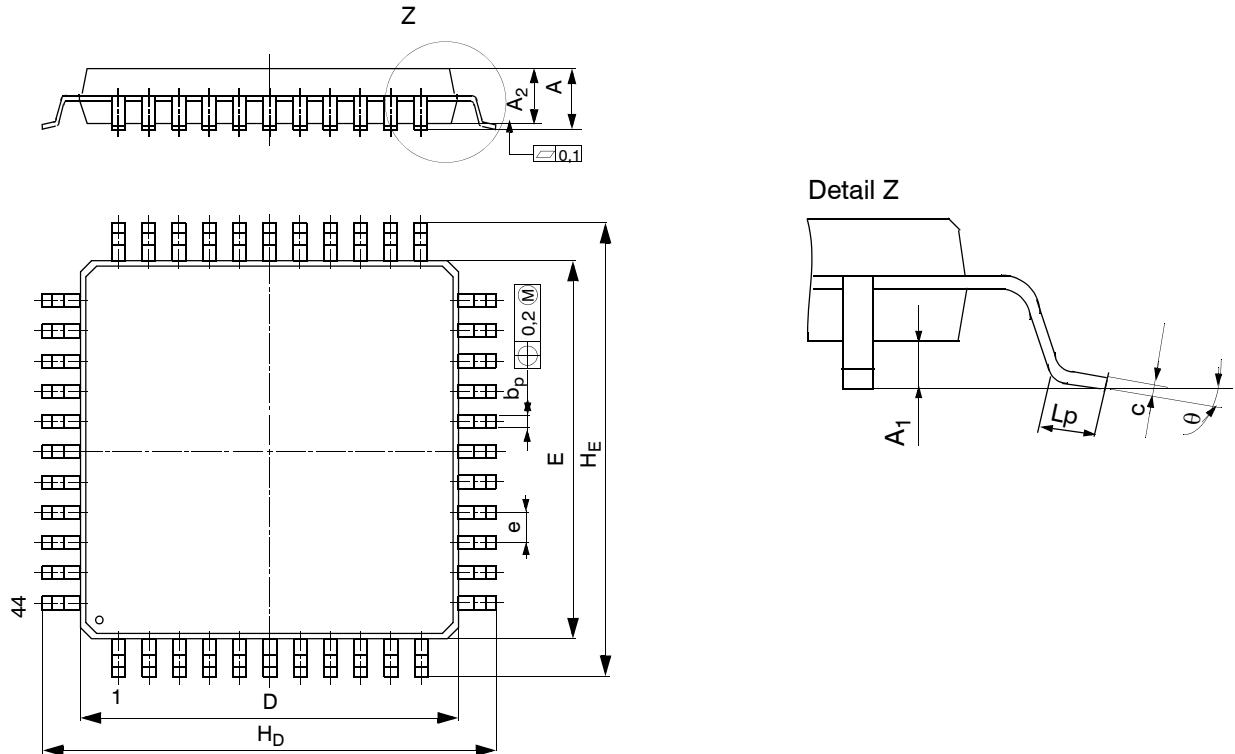
Zentrum Mikroelektronik Dresden AG		
Editor: signed Schoder	Date: 30.04.2002	Doc-No. QS-000758-HD-02
Check signed Marx	Quality signed Gersdorf:	

	<b>Package LQFP44 (10 x 10)</b>	<b>MDS 758</b>
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Dimensions in millimetres

Supersedes  
Edition 12.99

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